

**What is claimed is:**

1           1. A heat dissipating apparatus for an electronic  
2 device having an integrated heat spreader, comprising:

3           a base having a lower surface and an upper surface,  
4           the lower surface having a contact area to  
5           contact the integrated heat spreader when the  
6           base is disposed on the electronic device, and  
7           the lower surface having a concave area  
8           extended to the contact area from an edge of  
9           the lower surface of the base.

1           2. The heat dissipating apparatus as claimed in  
2 claim 1, wherein the contact area of the base is  
3 connected to the integrated heat spreader by means of  
4 thermal paste.

1           3. The heat dissipating apparatus as claimed in  
2 claim 2, wherein the thermal paste is composed of a phase  
3 change material.

1           4. The heat dissipating apparatus as claimed in  
2 claim 1, wherein the base further comprises a plurality  
3 of fins formed on the upper surface thereof.

1           5. The heat dissipating apparatus as claimed in  
2 claim 1, wherein the cross section of the concave area is  
3 rectangular.

1           6. The heat dissipating apparatus as claimed in  
2 claim 1, wherein the cross section of the concave area is  
3 semicircular.

1           7. The heat dissipating apparatus as claimed in  
2 claim 1, wherein the cross section of the concave area is  
3 triangular.

1           8. The heat dissipating apparatus as claimed in  
2 claim 1, wherein the integrated heat spreader and contact  
3 area are substantially rectangular.

1           9. The heat dissipating apparatus as claimed in  
2 claim 1, wherein the electronic device is a central  
3 processing unit (CPU).

1           10. A heat dissipating apparatus, disposed on an  
2 electronic device having an integrated heat spreader,  
3 comprising:

4           a base having a concave area and a contact area,  
5           wherein the contact area is connected to the  
6           integrated heat spreader, the shape and  
7           position of the contact area correspond to the  
8           shape and position of the integrated heat  
9           spreader, and the concave area is extended to  
10          the contact area from an edge of the base; and

11          a thermal paste disposed between the contact area  
12          and integrated heat spreader.

1           11. The heat dissipating apparatus as claimed in  
2 claim 10, wherein the thermal paste is composed of a  
3 phase change material.

1           12. The heat dissipating apparatus as claimed in  
2 claim 10, wherein the base further comprises a plurality  
3 of fins formed thereon.

1           13. The heat dissipating apparatus as claimed in  
2 claim 10, wherein the cross section of the concave area  
3 is rectangular.

1           14. The heat dissipating apparatus as claimed in  
2 claim 10, wherein the cross section of the concave area  
3 is semicircular.

1           15. The heat dissipating apparatus as claimed in  
2 claim 10, wherein the cross section of the concave area  
3 is triangular.